

## Silicon identification

This errata sheet applies to the M24256-BR and M24256-DF, which are 256 Kbit serial I<sup>2</sup>C bus EEPROMs, and specifically to the devices delivered in 8-bump wafer-level chip-scale packages (WLCSP).

[Table 1](#) shows the list of part numbers.

**Table 1. Device summary**

Reference	Part Number
M24256-BR	M24256-BRCS6TP/A
M24256-DF	M24256-DFCS6TP/K

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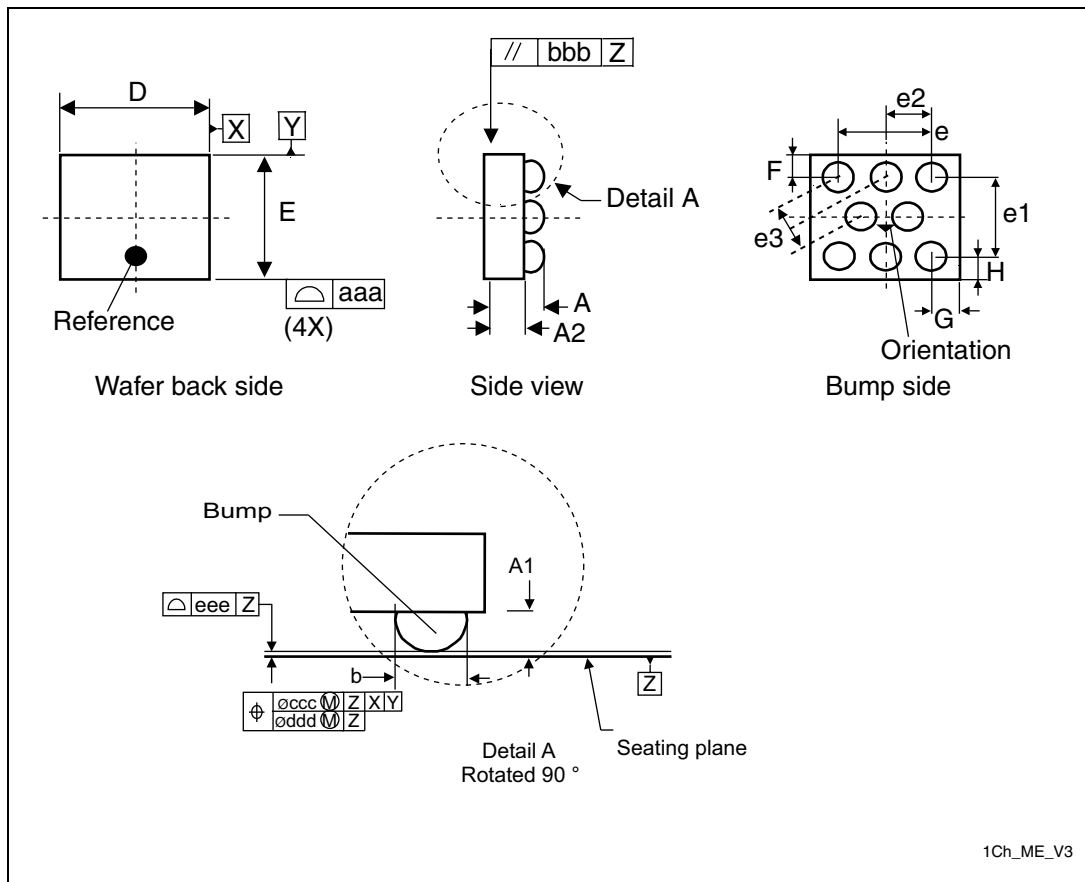
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# 1 M24256-BR and M24256-DF physical product change

There is not any physical product change.

*Figure 1* shows the package outline.

**Figure 1.** WLCSP 8-bump, without BSC, 1.289 x 1.376 mm, wafer level chip scale package outline



The figures below show the difference between  $D$  and  $E$  dimensions in the front side view (see *Figure 2*), back side view (see *Figure 3*) and side view (see *Figure 4*).

Figure 2. D and E front side view

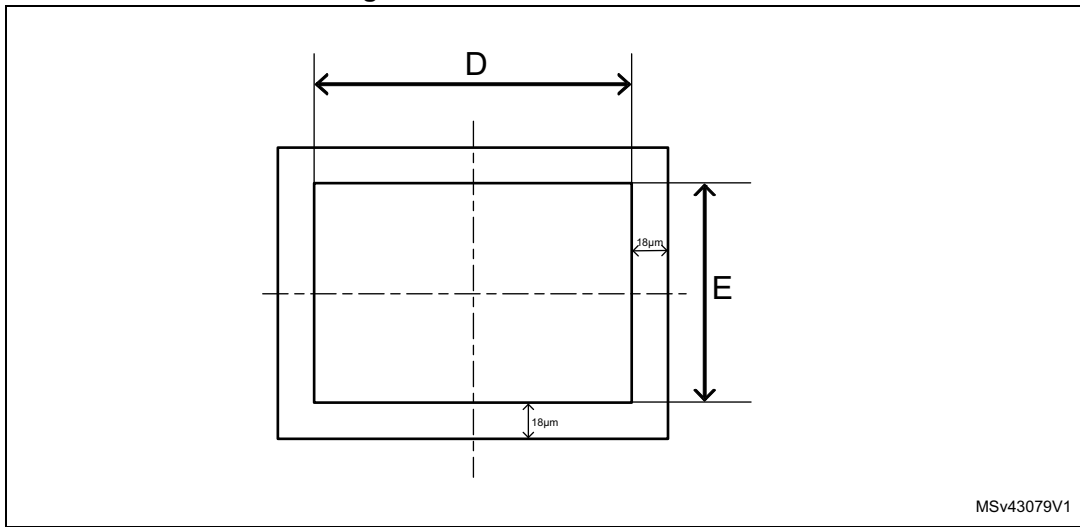


Figure 3. D and E back side view

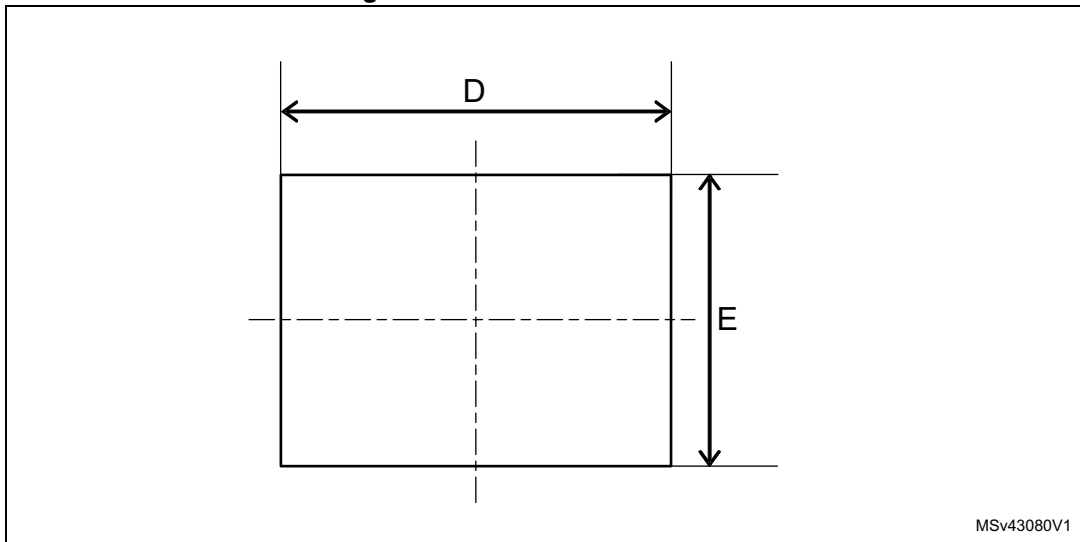
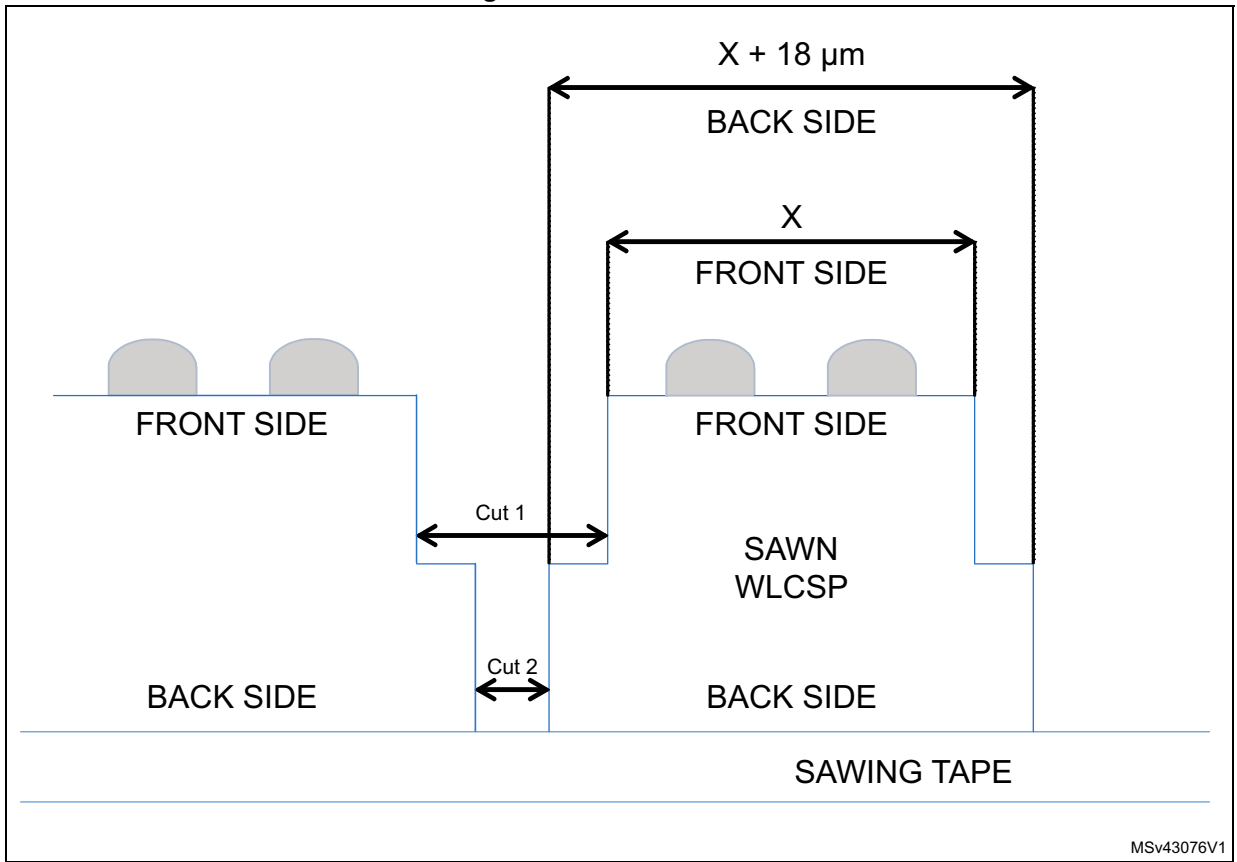


Figure 4. D or E side view



## 2 Package mechanical data modifications

This document refers to the changes in dimensions D and E (see [Figure 3](#)) described in the M24256-BR/M24256-DF datasheet, in tables detailing the dimensions of the WLCSP 8-bump package.

D and E values must be modified to correct the following mistake:

- The D and E values in the M24256-BR/M24256-DF datasheet correspond to front side view (ball side), instead of back side view (marking side view).  
[Table 2](#) and [Table 3](#) report the data for the front and back view, respectively.

**Table 2. D and E values corresponding to front side view**

Symbol	Millimeters			Inches		
	Min	Typ	Max	Min	Typ	Max
D	-	1.271	1.291	-	0.0500	0.0508
E	-	1.358	1.378	-	0.0535	0.0543

**Table 3. D and E values corresponding to back side view**

Symbol	Millimeters			Inches		
	Min	Typ	Max	Min	Typ	Max
D	-	1.289	1.309	-	0.0507	0.0515
E	-	1.376	1.396	-	0.0542	0.0550

The difference between back side and front side dimension is 18 µm (0.018 mm). This difference is due to the two-step sawing process, where cut 1 and cut 2 are performed with blades having different thicknesses (see [Figure 4](#) in which X represents D or E and it has the same value and tolerance).



### 3 Revision history

Table 4. Document revision history

Date	Revision	Changes
15-Jul-2016	1	Initial release.

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